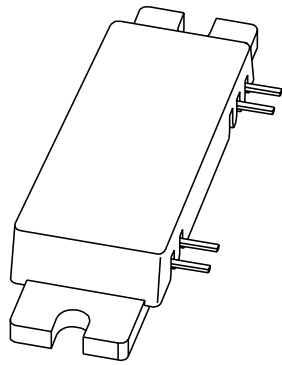


DATA SHEET



BGY1816 UHF amplifier module

Product specification
Supersedes data of 1998 Apr 09

1998 May 27

UHF amplifier module

BGY1816

FEATURES

- 26 V nominal supply voltage
- 16 W output power into a load of 50 Ω with an RF drive power of ≤63 mW.

APPLICATIONS

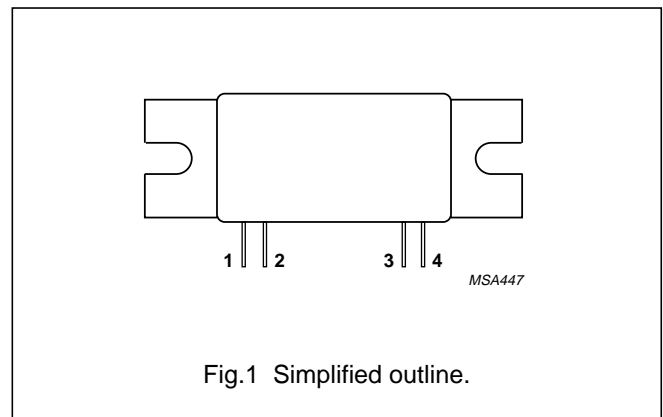
- Base station transmitting equipment operating in the 1805 to 1880 MHz frequency band.

DESCRIPTION

The BGY1816 is a three-stage UHF amplifier module in a SOT365A package with a plastic cap. It consists of three NPN silicon planar transistor dies mounted together with matching and bias circuit components on a metallized ceramic AlN substrate.

PINNING - SOT365A

| PIN | DESCRIPTION |
|--------|-----------------|
| 1 | RF input |
| 2 | V _{S1} |
| 3 | V _{S2} |
| 4 | RF output |
| Flange | ground |



QUICK REFERENCE DATA

RF performance at T_{mb} = 25 °C.

| MODE OF OPERATION | f (MHz) | V _{S1} (V) | V _{S2} (V) | P _L (W) | G _p (dB) | η (%) | Z _S ; Z _L (Ω) |
|-------------------|--------------|---------------------|---------------------|--------------------|---------------------|-------|-------------------------------------|
| CW | 1805 to 1880 | 5 | 26 | ≥16 | ≥24 | ≥30 | 50 |

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------|-------------------------------------|-------------------------|------|------|------|
| V _{S1} | DC supply voltage | | 4.5 | 5.5 | V |
| V _{S2} | DC supply voltage | | – | 28 | V |
| P _D | input drive power | | – | 120 | mW |
| P _L | load power | T _{mb} = 25 °C | – | 20 | W |
| T _{stg} | storage temperature | | –30 | +100 | °C |
| T _{mb} | operating mounting base temperature | | –10 | +90 | °C |

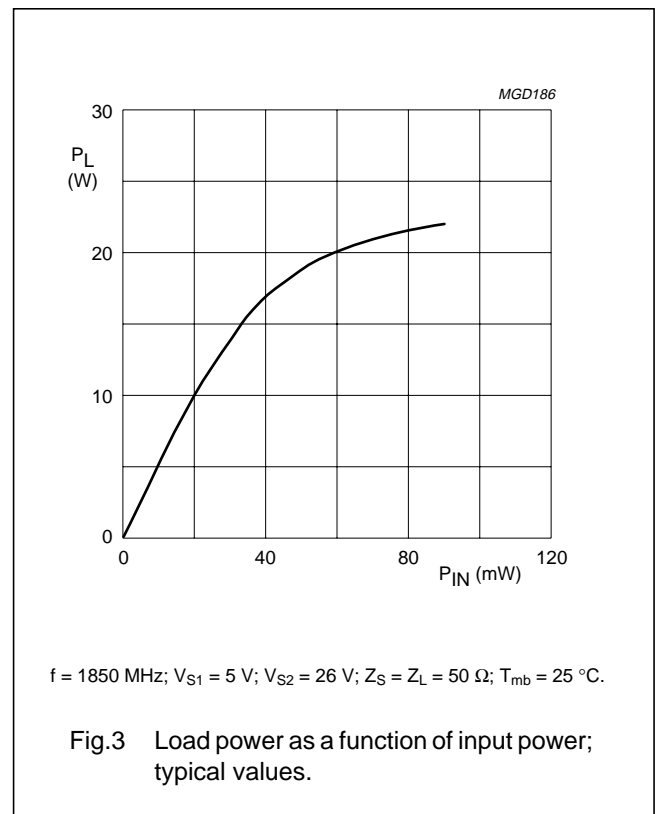
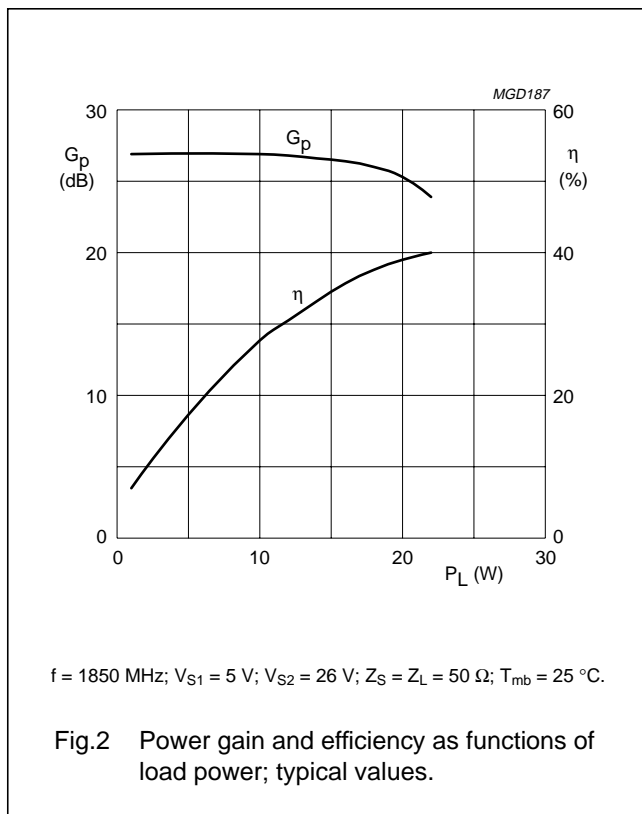
UHF amplifier module

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CHARACTERISTICS

$T_{mb} = 25\text{ }^{\circ}\text{C}$; $V_{S1} = 5\text{ V}$; $V_{S2} = 26\text{ V}$; $P_L = 16\text{ W}$; $Z_S = Z_L = 50\text{ }\Omega$ unless otherwise specified.

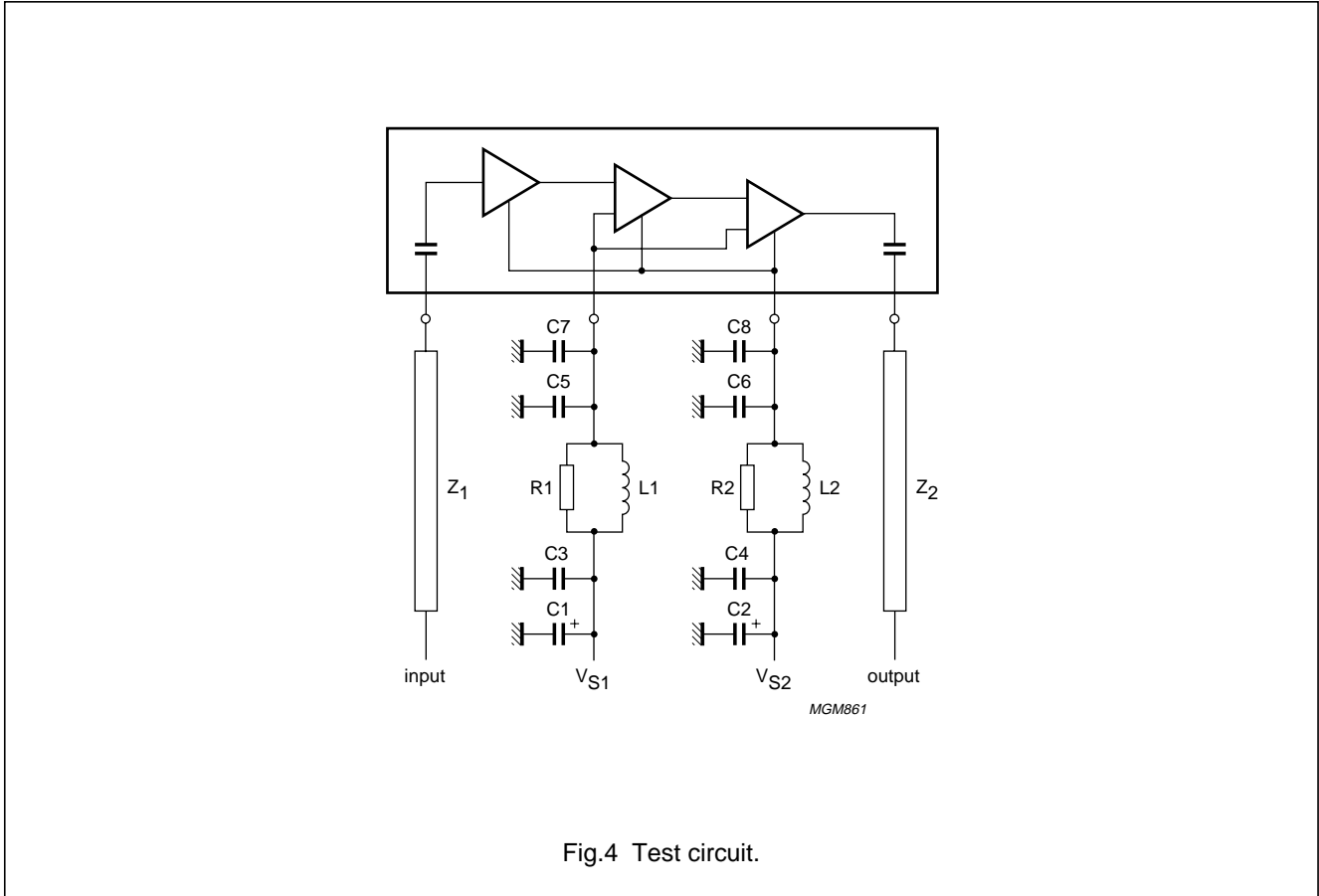
| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|----------------|-------------------------|--|----------------|------|---------|------|
| f | frequency | | 1805 | – | 1880 | MHz |
| I_{S1} | supply current | | – | 80 | – | mA |
| I_{S2} | supply current | $P_D < -60\text{ dBm}$ | – | 430 | – | mA |
| P_L | load power | $P_D < 63\text{ mW}$ | 16 | – | – | W |
| G_p | power gain | | 24 | – | 28 | dB |
| η | efficiency | | 30 | – | – | % |
| H_2 | second harmonic | | – | – | -35 | dBc |
| H_3 | third harmonic | | – | – | -40 | dBc |
| $V_{SWR_{in}}$ | input VSWR | | – | – | 1.6 : 1 | |
| | stability | $V_{SWR} \leq 2 : 1$ through all phases; $P_L \leq 16\text{ W}$; $V_{S2} = 25\text{ to }27\text{ V}$ | – | – | -60 | dBc |
| | reverse intermodulation | $P_{carrier} = 16\text{ W}$; $P_{reverse} = -40\text{ dBc}$; $f_i = f_c \pm 200\text{ kHz}$ | – | – | -53 | dBc |
| B | AM bandwidth | corner frequency = 3 dB; $P_{carrier} = 16\text{ W}$; modulation = 20% | 2 | – | – | MHz |
| | ruggedness | $V_{SWR} \leq 5 : 1$ through all phases | no degradation | | | |



UHF amplifier module

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APPLICATION INFORMATION



List of components (see Figs 4 and 5)

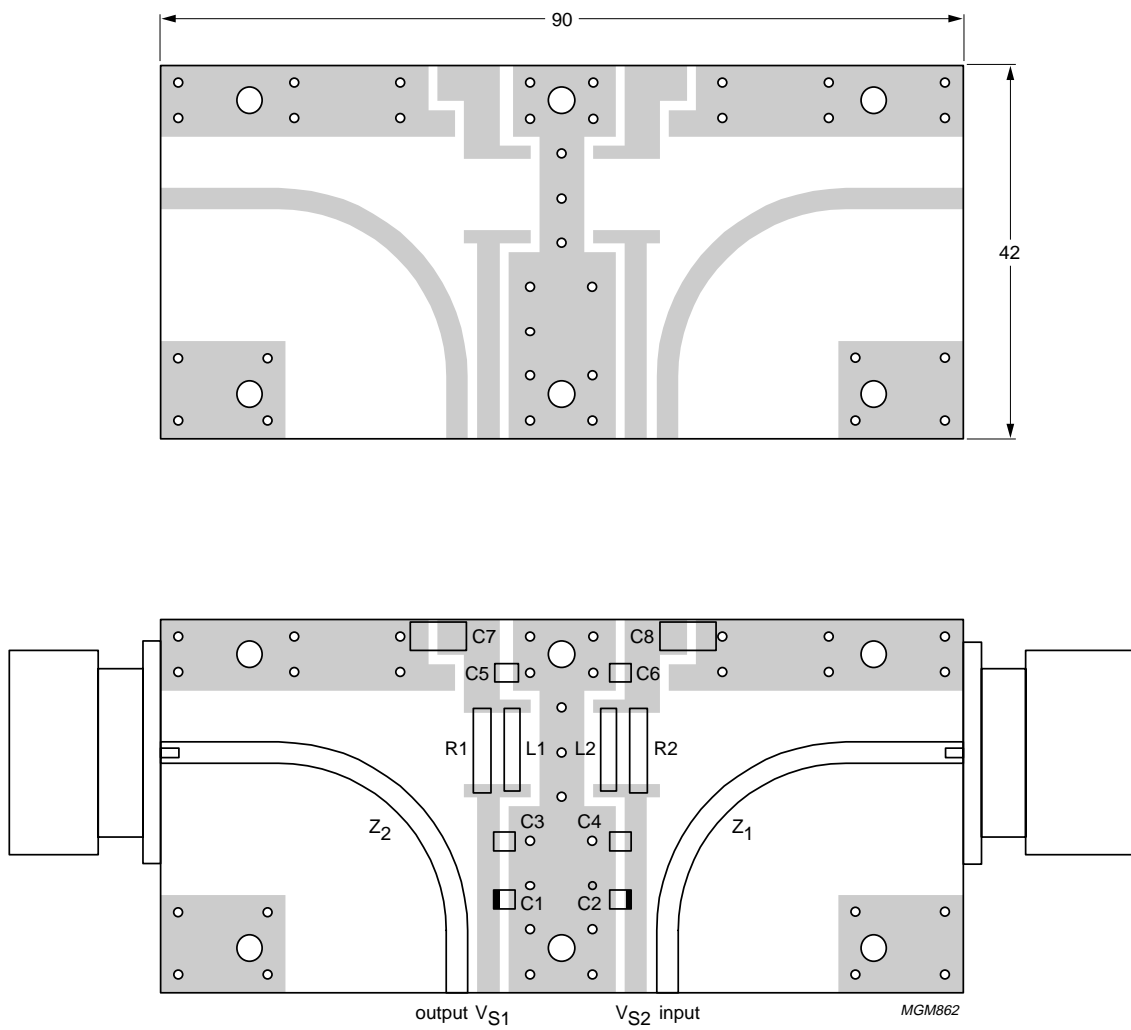
| COMPONENT | DESCRIPTION | VALUE | CATALOGUE NO. |
|-----------|-----------------------------------|---------------------|----------------|
| C1, C2 | electrolytic capacitor | 10 μ F; 35 V | |
| C3, C4 | multilayer ceramic chip capacitor | 10 nF; 50 V | |
| C5, C6 | multilayer ceramic chip capacitor | 100 pF; 50 V | |
| C7, C8 | multilayer ceramic chip capacitor | 10 pF; 50 V | |
| L1, L2 | Grade 4S2 Ferroxcube bead | | 4330 030 36300 |
| R1, R2 | metal film resistor | 10 Ω ; 0.4 W | 2322 195 13109 |
| Z1, Z2 | stripline: note 1 | 50 Ω | |

Note

1. The striplines are on a double copper-clad printed-circuit board with epoxy dielectric ($\epsilon_r = 4.5$); thickness = 1 mm.

UHF amplifier module

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Dimensions in mm.

Fig.5 Printed-circuit board component layout.

UHF amplifier module**BGY1816**

MOUNTING RECOMMENDATIONS

To ensure a good thermal contact and to prevent mechanical stress when bolted down, the flatness of the mounting base is designed to be typically better than 0.1 mm. The mounting area of the heatsink should be flat and free from burrs and loose particles. The heatsink should be rigid and not prone to bowing under thermal cycling conditions. The thickness of a solid heatsink should be not less than 5 mm to ensure a rigid assembly.

A thin, even layer of thermal compound should be applied between the mounting base and the heatsink to achieve the best possible thermal contact resistance. Excessive use of thermal compound will result in an increase in thermal resistance and possible bowing of the mounting base; too little will also result in poor thermal conduction.

The module should be mounted to the heatsink using 3 mm bolts with flat washers. The bolts should first be tightened to "finger tight" and then further tightened in alternating steps to a maximum torque of 0.4 to 0.6 Nm.

Once mounted on the heatsink, the module leads can be soldered to the printed-circuit board. A soldering iron may be used up to a temperature of 250 °C for a maximum of 10 seconds at a distance of 2 mm from the plastic cap.

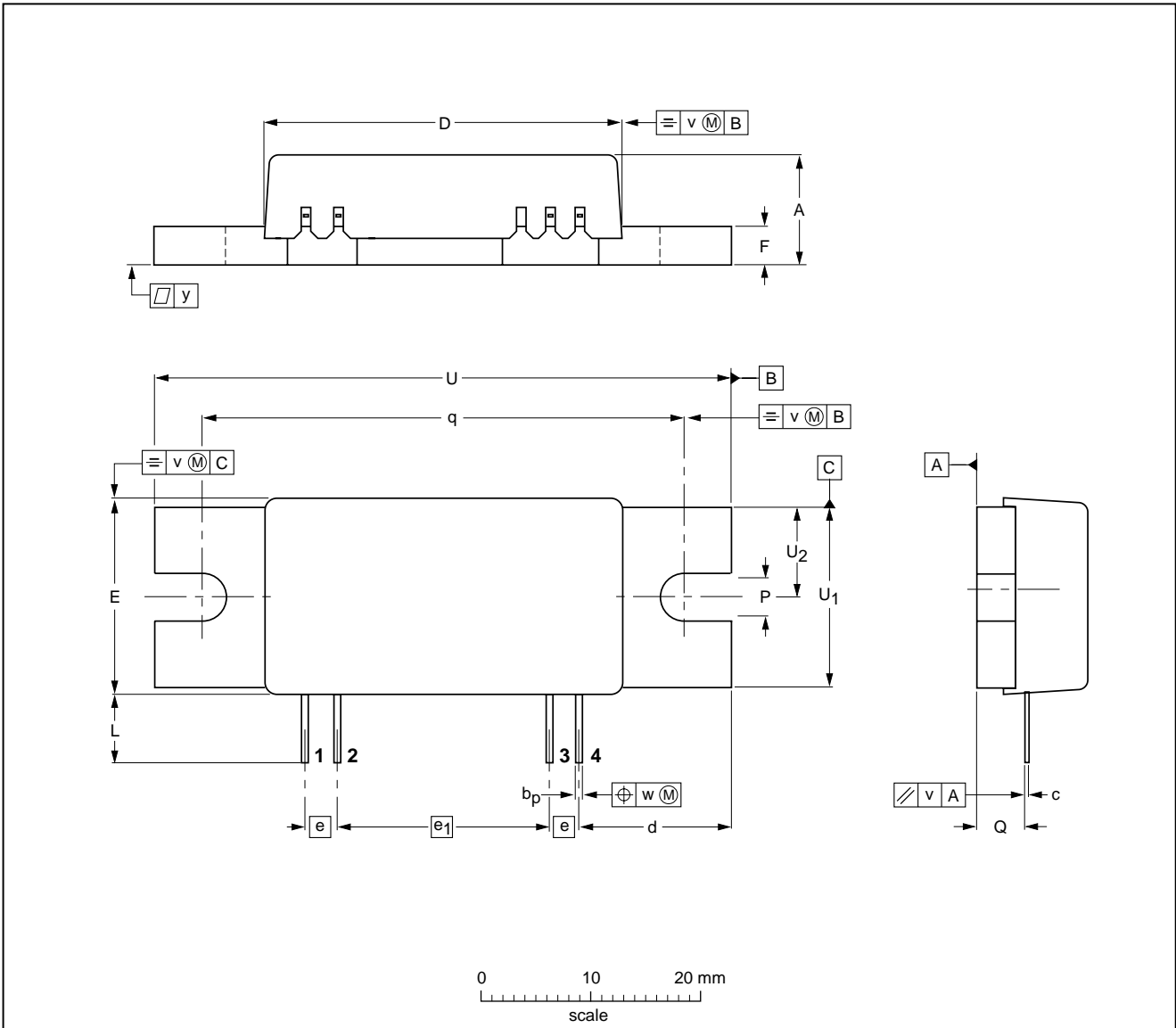
ESD precautions must be taken to protect the device from electrostatic damage.

UHF amplifier module

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PACKAGE OUTLINE

Plastic rectangular single-ended flat package; flange mounted; 2 mounting holes; 4 in-line leads SOT365A



DIMENSIONS (mm are the original dimensions)

| UNIT | A | b _p | c | D | d | E | e | e ₁ | F | L | P | Q | q | U | U ₁ | U ₂ | v | w | y |
|------|------------|----------------|------------|--------------|--------------|--------------|------|----------------|--------------|------------|------------|------------|----------------|--------------|----------------|----------------|-----|------|-----|
| mm | 9.5 9.0 | 0.56 0.46 | 0.3 0.2 | 30.1 29.9 | 12.8 12.6 | 18.6 18.4 | 2.54 | 17.78 | 3.25 3.15 | 6.5 6.1 | 4.1 3.9 | 4.0 3.8 | 40.74 40.54 | 48.0 48.4 | 15.4 15.2 | 7.75 7.55 | 0.2 | 0.25 | 0.1 |

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|------|--|---------------------|------------|
| | IEC | JEDEC | EIAJ | | | |
| SOT365A | | | | | | 97-05-25 |

UHF amplifier module

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DEFINITIONS

| Data Sheet Status | |
|---|---|
| Objective specification | This data sheet contains target or goal specifications for product development. |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification | This data sheet contains final product specifications. |
| Limiting values | |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. | |
| Application information | |
| Where application information is given, it is advisory and does not form part of the specification. | |

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NOTES

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NOTES

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